

# semiconductor packaging news

## EV Group Unlocks Production Scaling with Step-and-Repeat Nanoimprint Lithography System – June 9, 2021

# semiconductor packaging news

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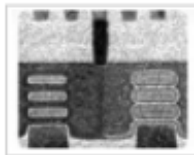
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June 9, 2021

### TSMC's Chip Scaling Efforts Reach Crossroads at 2nm

Perpetuating Moore's Law -- the observation that the transistor density in a typical chip doubles every two years -- poses a number of challenges at the 3nm node, yet Taiwan Semiconductor Manufacturing Corp. (TSMC) remains optimistic. There are many predictions Moore's Law is likely to hit a wall soon, but "how soon?" is open to debate. Also, there are technologies that promise ongoing ...

EE Times



### Prevent Costly Die Migration.

Avoid the high costs associated with die migration from the pockets of chip trays with Gel-Pak's New LCS2™ Waffle Pack Lid. Learn more.

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### High Force and Large area bond tester

The most powerful bond tester to test IGBTs, power modules and large batteries up to 1000 kgf. Sigma HF/L offers flexible positioning and operates with the fastest axis speed. Learn more.



### GlobalFoundries seeks ruling in IBM contract dispute

Semiconductor manufacturer GlobalFoundries sued International Business Machines Corp, asking a judge to rule that it did not violate a contract with the U.S. company ...

Reuters

### Justifying the Purchase of Die or Wire Bonding Equipment

The justification for new die or wire bonding equipment needs to be clear, focused, and precise enough for management to approve the use of funds to make ...

Technical Paper

### Reliability Costs Becoming Harder To Track

Ensuring reliability in chips is becoming more complex and significantly more expensive, shifting left into the design cycle and right into the field. But those costs also ...

Semiconductor Engineering

### Technical Papers

- [Innovations in Wire Bond Inspection](#)
- [Customized Assembly Process for Hermetic Devices](#)
- [CF4-free Microwave Induced Plasma Decapsulation of Automotive Semiconductor Devices](#)
- [Optimizing Insertion Extraction Force in a Pin-Socket Interconnect](#)
- [Hermetic Package Process Development](#)
- [Justifying the Purchase of Die or Wire Bonding Equipment](#)
- [Die-to-wafer Bonding Accelerates Heterogeneous Integration \(HI\)](#)

### Better Bonds, with Atmospheric Plasma

Our Atmospheric Plasma systems prepare surfaces for direct bonding, remove residue, and prepare surfaces for adhesion. [Click Here](#) to learn more.

Ontos Equipment Systems



### The Gold Standard of Bond Testing

Royce Instruments has been designing and building bond test equipment for over 30 years. The line of bond test equipment offers unmatched precision & robust operation for all your needs.

Royce Instruments



### GlobalFoundries accuses IBM of seeking 'payday'

GlobalFoundries Inc asked a judge to rule that it does not owe US\$2.5 billion to International Business Machines Corp (IBM) over a 2014 deal in which the semiconductor ...

Taipei Times

### 3 Technologies That Will Challenge Test

### MRSI next generation submicron die bonder

MRSI-S-HVM 0.5 micron die bonder, designed for integrated photonics volume manufacturing and semiconductor wafer level packaging.

MRSI Systems



Today's Sponsor

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### Test Your Knowledge

William Shockley is recognized as the father of what?  
See answer below.

### Advanced SiP Virtual Conference

The top global virtual event for Advanced System-in-Package technologies! One event covering SiP technology developments, solutions and business trends. Register now! August 9-12.

IMAPS



### Press Releases

### EV Group Unlocks Production Scaling with Step-and-Repeat Nanoimprint Lithography System

EV Group (EVG) announced the EVG@:770 NT-- its next-generation step-and-repeat nanoimprint lithography (NIL) system. The EVG770 NT enables precise replication of micro- ...

EV Group

### Accelerating its Globalization, JCET Completes Acquisition of ADI's Singapore Test Facility

JCET Group announced that it has officially completed the acquisition of Analog Devices Inc.'s ("ADI") Singapore test facility, with its test staff to be transferred to the JCET operations ...

JCET Group Co., Ltd.

### High-end inertial sensors market: Analog Devices is staying strong with its industrial MEMS IMUs

"For the development of robotics, smart agriculture, autonomous vehicles and navigation and stabilization applications, accurate motion capture sensors have played a central role ...

Yole Développement

### Die-Module Attach (Pastes & Films)

Die-Attach Adhesives with low moisture absorption for MSL Level-1 applications for reliability. Outstanding thermal conductivity with low moisture absorption--stress-free bonding.

AI Technology, Inc.



As chips are deployed in more complex systems and with new technologies, it's not clear exactly what chipmakers and systems vendors will be testing. The standard ...

**Semiconductor Engineering**

**The microchip shortage is one of the unforeseen outcomes of the pandemic**

The world runs on microchips. Not just the elaborate ones at the heart of your phone or laptop but mostly a lot of ordinary ones that you aren't even aware of. ...

CNET



**GF, GlobalWafers extend partnership**

Globalfoundries has announced that the foundry and silicon wafer supplier GlobalWafers have struck a US\$800 million agreement to add 300mm silicon-on-insulator ...

Digitimes

**Expanded Material Metrology For Refined Etch Selectivities**

Trends in advanced device fabrication require combined lithography-etching multi-patterning sequences and self-aligned multi-patterning to form devices' finest ...

Semiconductor Engineering

**Nvidia asks Chinese regulators to approve \$40 billion Arm deal**

Nvidia Corp has submitted an application to Chinese competition regulators to review a \$40 billion takeover of UK chip designer Arm, the Financial Times reported on ...

Reuters

**Accelerating Heterogeneous Integration (HI)**  
EVG provides world-class wafer-to-wafer and die-to-wafer hybrid bonding process solutions that help customers speed the deployment of HI technologies.  
EV Group



**Alternatives to Isopropyl Alcohol (IPA)**  
Having a hard time finding IPA? KYZEN offers safe, affordable alternatives globally! To learn more, fill out this form to download our technical brief!  
KYZEN



**Samsung looking to expand 7th generation V-NAND solutions**

Samsung Electronics Co. aims to expand the use of its seventh generation V-NAND chip solutions, a senior executive said, as the South Korean tech giant eyes to bolster ...

Yonhap News Agency


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**Quote of the Day**

Ability is what you're capable of doing. Motivation determines what you do. Attitude determines how well you do it.

Lou Holtz

**Die-Module Attach (Pastes & Films)**  
Die-Attach Adhesives with low moisture absorption for MSL Level-1 applications for reliability. Outstanding thermal conductivity with low moisture absorption-stress-free bonding.  
AI Technology, Inc.



**Tired of Your Legacy Tool Breaking?**  
Revolutionary productivity for your advanced technologies! The YES-EcoClean Plasma Resist Strip/Descum System is 1/3 the capital cost of comparative products. Read more here...  
Yield Engineering Systems, Inc.



**What Year Was It? Secretariat Wins Triple Crown**

With a spectacular victory at the Belmont Stakes, Secretariat becomes the first horse since Citation in 1948 to win America's coveted Triple Crown.



**The day was Jun 9. What year was it?**

**EMI Protection at the Package Level**  
Miniaturization and SIP advances are driving a need for more effective EMI shielding at the package level. Two new approaches from Henkel are providing unique solutions to this challenge.  
Henkel Electronics, Inc.



**IC Packaging Issues**  
As ICs become faster, smaller and more complex the need for innovative packaging solutions has increased including SIP, MCM, RF Modules and Stacked assemblies.  
Integra Technologies



**Cartoon of the Day**



"On Mondays, I get ready to plan my week. On Tuesdays, I plan my week. On Wednesdays, I revise my plan for the week. On Thursdays, I put

## Calendar

- [Jun 9, 2021: ITF USA 2021](#)
- [Jun 9, 2021: ECTC Virtual Conference](#)
- [Jun 22, 2021: Hardware to Highlight Leti Innovation Days](#)
- [Jun 22, 2021: 2021 International Conference on System-in-Package \(SiP\) Technology](#)

### Accelerating Heterogeneous Integration (HI)

EVG provides world-class wafer-to-wafer and die-to-wafer hybrid bonding process solutions that help customers speed the deployment of HI technologies.

**EV Group**



### Alternatives to Isopropyl Alcohol (IPA)

Having a hard time finding IPA? KYZEN offers safe, affordable alternatives globally! To learn more, fill out this form to download our technical brief!

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my plan for the week into my computer. On Fridays I think about starting my plan for next week."

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Increase throughput with the NanoResolution MRS Sensor that is 2-3X faster, delivering greater than 25 wafers (300mm) per hour. Learn more.

**CyberOptics Corporation**



### Test Your Knowledge Answer

William Shockley is recognized as the father of what?

Answer: The Transistor. Shockley was an American physicist and inventor. With John Bardeen and Walter Brattain were jointly awarded the 1956 Nobel Prize in Physics for "their researches on semiconductors and their discovery of the transistor effect."

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